

## Memorandum

**To:** R.M. Schafer  
**From:** Smart Windows  
**Date:** April 15, 2010  
**Subject:** Meeting Minutes

- 1.) Updates
  - a. Board Progress
    - i. Board and sample parts are in
  - b. Software
    - i. Dave and Andy will meet next week
- 2.) Meetings
  - a. Meeting next week.
- 3.) Notes on using equipment
  - a. Tape down board
  - b. Tape down solder screen over board with tape along one side
  - c. Place parts
  - d. Alignment critical on transceiver pin
  - e. Make sure orientation of part is correct
  - f. Will probably have to redo for each board
  - g. Let circuit board sit for a min or two heating
  - h. Get solder sucking device
  - i. Set air flow as flow as possible (usually)
  - j. "Dance over top"
  - k. Try one first, then do all the rest as a batch
  - l. Solder paste is in the back of the refrigerator